

HVM14S

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0113-0500Z (Previous: ADE-208-083D) Rev.5.00 Oct.08.2003

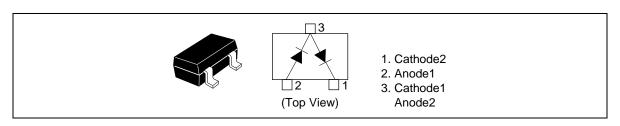
Features

- Low forward resistance. ($r_f = 7.0 \Omega \text{ max}$)
- Low capacitance. (C = 0.25 pF typ)
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVM14S	H6	MPAK

Pin Arrangement



Absolute Maximum Ratings *1

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Reverse voltage	V_R	50	V	
Forward current	l _F	50	mA	
Power dissipation	Pd	100	mW	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Note: 1. Absolute maximum ratings are described each unit separately.

Electrical Characteristics *1

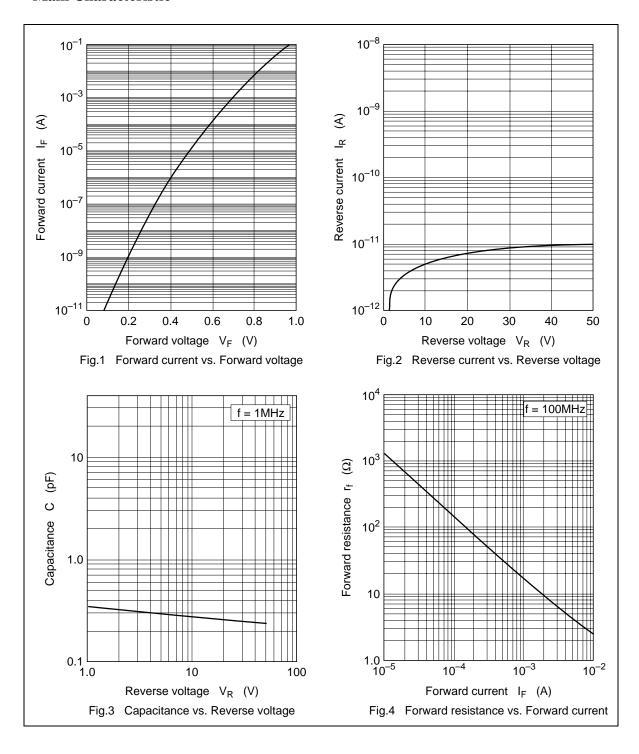
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	1.0	V	I _F = 50 mA
Reverse current	I _R	_	_	100	nA	V _R = 50 V
Capacitance	С	_	0.25	_	pF	V _R = 50 V, f = 1 MHz
Forward resistance	r _f	_	_	7.0	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability *2	_	200	_	_	V	C = 200 pF, Both forward and reverse direction 1 pulse.

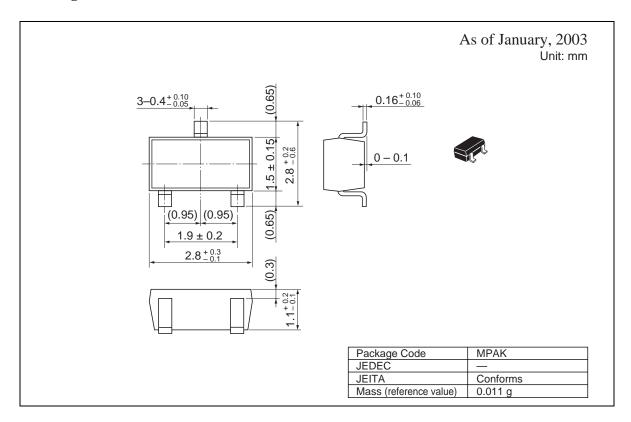
Notes: 1. Per one device.

2. Failure criterion; $I_R \geq 200 \text{ nA}$ at V_R = 50 V

Main Characteristic



Package Dimensions



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